

Kulicke & Soffa to Participate at IPC APEX EXPO 2018

SINGAPORE--(BUSINESS WIRE)--Feb. 26, 2018-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) (“Kulicke & Soffa”, “K&S” or the “Company”), announced today that it will be exhibiting at the IPC APEX EXPO 2017 trade show from February 27 to March 1, 2018.

Kulicke & Soffa will be showcasing its market leading packaging solutions at San Diego Convention Center, Booth Number 3819.

- iFlex T2 – its new design increases feeder capacity by 25% while also excelling at multi-part tray feeding. This multifunctional flexibility makes it a perfect standalone or end-of-line solution for the most demanding, high-mix applications.
- Hybrid Wafer Feeder – an innovative solution that enables the combination of ultra-high-speed passive and active placement with high-accuracy flip-chip bonding directly from wafer, ideal for high-volume System-in-Package (SiP), flip-chip, die-attach and wafer-level-package manufacturing. Placement accuracy up to 7µm @ 3 sigma, provides a compelling alternative to existing commercial solutions.

Chan Pin Chong, Kulicke & Soffa’s Senior Vice President for EA/APMR & Wedge Bonder Business Units, said, “Driven by increasing automotive demand, ongoing deployment of connected devices, and the perpetual growth of global electronic consumption, the semiconductor and electronic market will continue to evolve increasing assembly complexity for our customers. Our broadening portfolio, strategic R&D investments and product development roadmap will continue to provide competitive, value-additive solutions for this ever-evolving market space.”

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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